Leiditech

HL600-110~160 Series

Positive Thermal Coefficent Diodes

Features：

- ✧ Radial leaded Devices
- ✧ Cured,flame retardant epoxy polymer insulating material meets UL94V-0
- ✧ Rohs compliant and lead-free

Product Dimensions

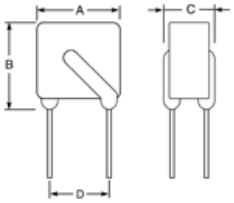


Fig1

Unit :mm

Model	Dimensions（mm）				Lead material	Shape
	A(max)	B(max)	C(max)	D(typ)	Tinned matel(mm)	Fig
HL600-110	15	15	5.5	5.1	22AWG/Φ0.6	1
HL600-150	15	15	5.5	5.1	22AWG/Φ0.6	1
HL600-160	15	15	5.5	5.1	22AWG/Φ0.6	1

Note: Dimensions in the A, B, C are the maximum sizes, all typical values of D is the tolerance of ± 0.75mm.

Thermal Derating Chart- I_H（A）

Model	Maximum ambient operating temperatures（℃）								
	-40℃	-20℃	0℃	25℃	*40℃*	50℃	60℃	70℃	85℃
HL600 -110	0.162	0.152	0.131	0.11	*0.913*	0.0803	0.0704	0.0605	0.0462
HL600-150	0.221	0.207	0.178	0.15	0.125	0.110	0.096	0.825	0.063
HL600-160	0.235	0.221	0.190	0.16	0.133	0.117	0.102	0.088	0.0672

Electrical Characteristics

Model	Ih（A）	It(A)	Vmax interrupt（V）	Imax（A）	P_d（W）	Maximum Time to Trip		Resistance(Ω)
						Current（A）	Time（S）	R_{min}- R_{max}
HL600-110	0.11	0.22	600	3	1.0	1.0	8	6-16
HL600-150	0.15	0.30	600	3	1.0	1.0	9	5-14
HL600-160	0.16	0.32	600	3	1.0	1.0	10	4-12

I_h=Hold current:Maximum current at which the device will not interruptin 25℃ still air.

I_t=Trip current:Minimum current at which the device from low resistance to high resistance in 25℃ still air.

V_{max}=Maximum continuous voltage device can withstand without damage at rated current.

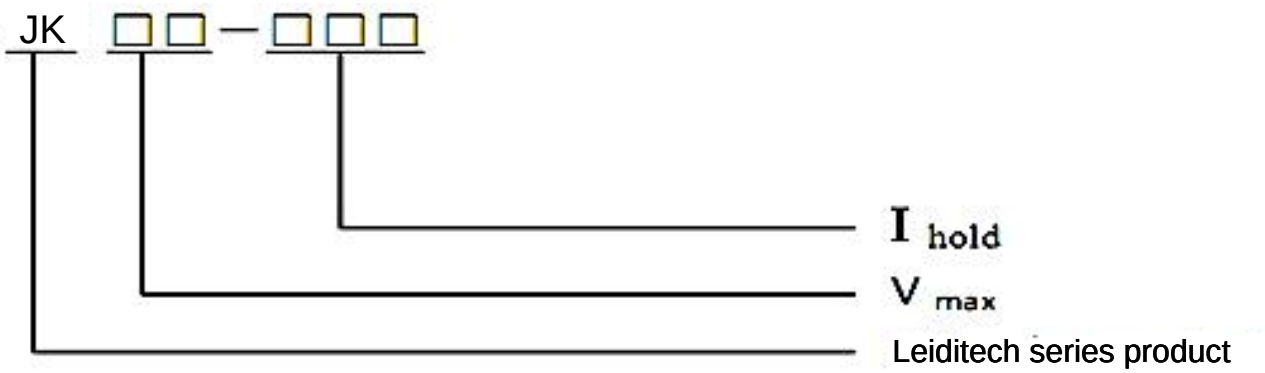
I_{max}=Maximum fault current device can withstand without damage at rated voltage.

T_{trip}=Maximum time to trip(s) at assigned current.

P_d=Typical power dissipation:Typical amount of power dissipated from the device when in 25℃ still air environment.

R_{min}=Minimum resistance of device at 25℃ prior to tripping.

Marking System



Environmental Specifications

Test	Conditions	Resistance change
Passive aging	+85℃，1000 hours	±8% typical
Humidity aging	+85℃，85%R.H.1000 hours	±8% typical
Thermal shock	+125℃ to -55℃，10 Times	±12% typical
SolventResistance	MIL-STD-202，Method 215F	No change
Vibration	MIL-STD-202，Method 201	No change

Soldering method

Wave Soldering：

Soldering Temperature:260℃~270℃

Soldering Time:≤3sec.

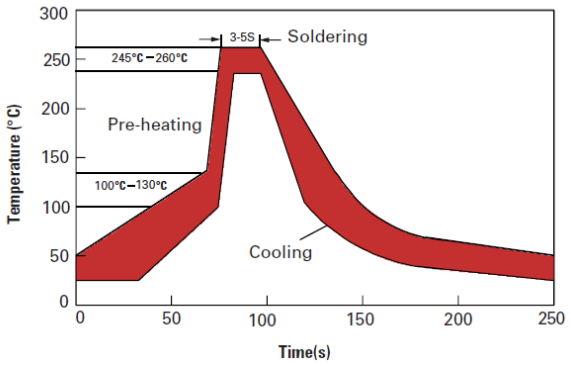
Soldering Position: Resettable fuse wire and the bottom ≥ 6mm。

Manual soldering：

Soldering Temperature:250℃~280℃

Soldering Time: ≤3sec.

Soldering Position: Resettable fuse wire and the bottom ≥ 6mm。



Packaging and Storage

Packaging quantity

HL600-110～HL600-160200 Pcs/Bag

Storage

The maximum ambient temperature shall not exceed 40℃.Storage temperature higher than 40℃ could result in the deformation of packaging materials.The maximum relative humidity recommended for storage is 70%.High humidity with high temperature can accelerate the oxidation of the solder plating on the leads and reduce the solderability of the components.Sealed plastic bags with desiccant shall be used to reduce the oxidation of the leads and shall only be opened prior to use.The products shall not be stored in areas where harmful gases containing acid or alkali or other harmful substancesare present.

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